

Global Power Packaging for Automotive Semiconductors Supply, Demand and Key Producers, 2023-2029

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Abstracts

The global Power Packaging for Automotive Semiconductors market size is expected to reach \$ 2215.2 million by 2029, rising at a market growth of 8.3% CAGR during the forecast period (2023-2029).

Currently the key players of Automotive OSAT are Amkor, ASE Group and UTAC, Others Automotive OSAT players are mainly located in China Taiwan, South Korea, China mainland, Southeast Asia (Singapore and Malaysia), including Chipbond Technology Corporation, ChipMOS TECHNOLOGIES, Powertech Technology Inc. (PTI), King Yuan Electronics Corp. (KVEC), OSE CORP., Sigurd Microelectronics, Natronix Semiconductor Technology, Nepes, SFA Semicon, Unisem Group, Carsem, Union Semiconductor?Hefei?Co., Ltd., Tongfu Microelectronics (TFME), Hefei Chipmore Technology Co.,Ltd., JCET Group and HT-tech, etc.

Automotive electronics encompasses a variety of products – from body electronics and access systems to engine, lighting and infotainment components. This report studies the Power Packaging for Automotive Semiconductors.

This report studies the global Power Packaging for Automotive Semiconductors demand, key companies, and key regions.

This report is a detailed and comprehensive analysis of the world market for Power Packaging for Automotive Semiconductors, and provides market size (US\$ million) and Year-over-Year (YoY) growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of Power Packaging for Automotive Semiconductors that contribute to its increasing demand

across many markets.

Highlights and key features of the study

Global Power Packaging for Automotive Semiconductors total market, 2018-2029, (USD Million)

Global Power Packaging for Automotive Semiconductors total market by region & country, CAGR, 2018-2029, (USD Million)

U.S. VS China: Power Packaging for Automotive Semiconductors total market, key domestic companies and share, (USD Million)

Global Power Packaging for Automotive Semiconductors revenue by player and market share 2018-2023, (USD Million)

Global Power Packaging for Automotive Semiconductors total market by Type, CAGR, 2018-2029, (USD Million)

Global Power Packaging for Automotive Semiconductors total market by Application, CAGR, 2018-2029, (USD Million).

This reports profiles major players in the global Power Packaging for Automotive Semiconductors market based on the following parameters – company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include NXP, Infineon (Cypress), Renesas, Texas Instrument, STMicroelectronics, Bosch, onsemi, Mitsubishi Electric and Rohm, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Power Packaging for Automotive Semiconductors market.

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), by player, by regions, by Type, and by Application. Data is given for the years

2018-2029 by year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

Global Power Packaging for Automotive Semiconductors Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Power Packaging for Automotive Semiconductors Market, Segmentation by Type

Diodes

IGBT

MOSFET

Power Management IC

Others

Global Power Packaging for Automotive Semiconductors Market, Segmentation by Application

Automotive OSAT

Automotive IDM

Companies Profiled:

NXP

Infineon (Cypress)

Renesas

Texas Instrument

STMicroelectronics

Bosch

onsemi

Mitsubishi Electric

Rohm

Microchip (Microsemi)

Amkor

ASE (SPIL)

UTAC

JCET (STATS ChipPAC)

Carsem

King Yuan Electronics Corp. (KYEC)

KINGPAK Technology Inc

Powertech Technology Inc. (PTI)

SFA Semicon

Unisem Group

Chipbond Technology Corporation

ChipMOS TECHNOLOGIES

OSE CORP.

Sigurd Microelectronics

Natronix Semiconductor Technology

Nepes

KESM Industries Berhad

Forehope Electronic (Ningbo) Co.,Ltd.

Union Semiconductor?Hefei?Co., Ltd.

Tongfu Microelectronics (TFME)

HT-tech

China Wafer Level CSP Co., Ltd

Ningbo ChipEx Semiconductor Co., Ltd

Guangdong Leadyo IC Testing

Unimos Microelectronics (Shanghai)

Sino Technology

Taiji Semiconductor (Suzhou)

Key Questions Answered

1. How big is the global Power Packaging for Automotive Semiconductors market?
2. What is the demand of the global Power Packaging for Automotive Semiconductors market?
3. What is the year over year growth of the global Power Packaging for Automotive Semiconductors market?
4. What is the total value of the global Power Packaging for Automotive Semiconductors market?
5. Who are the major players in the global Power Packaging for Automotive Semiconductors market?

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